

C0603X390G1HACTU

Aliases (C0603X390G1HAC7867) SMD Comm X8R HT150C Flex, Ceramic, 39 pF, 2%, 100 VDC, X8R, SMD, MLCC, High Temperature, Ultra-Stable, 0603, 0.4 mm



Click here for the 3D model.

| General Information | |
|--------------------------|--|
| Series | SMD Comm X8R HT150C Flex |
| Style | SMD Chip |
| Description | SMD, MLCC, High Temperature, Ultra-Stable |
| Features | Ultra-Stable |
| RoHS | Yes |
| Termination | Flexible Termination |
| Marking | No |
| AEC-Q200 | No |
| Typical Component Weight | 7.3 mg |
| Shelf Life | 78 Weeks |
| MSL | 1 |

| Specifications | |
|--|--|
| Capacitance | 39 pF |
| Measurement Condition | 1 MHz 1.0Vrms |
| Tolerance | 2% |
| Voltage DC | 100 VDC |
| Dielectric Withstanding Voltage | 250 VDC |
| Temperature Range | -55/+150°C |
| Temp. Coefficient | X8R |
| Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC) | 15%, 1MegaHz 1.0Vrms |
| Dissipation Factor | 2.5% 1 MHz 1.0Vrms |
| Aging Rate | 0% Loss/Decade Hour: Referee Time is 1000 Hours |
| Insulation Resistance | 100 GOhms |

 Dimensions

 Chip Size
 0603

 L
 1.6mm +/-0.17mm

 W
 0.8mm +/-0.15mm

 T
 0.8mm +/-0.15mm

 S
 0.4mm MIN

 B
 0.45mm +/-0.15mm

Packaging Specifications

| Packaging T& | R, 180mm, Paper Tape |
|-----------------------|----------------------|
| Packaging Quantity 40 | 000 |

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